

# HSF

**NOTES:**

Current Rating: 2.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

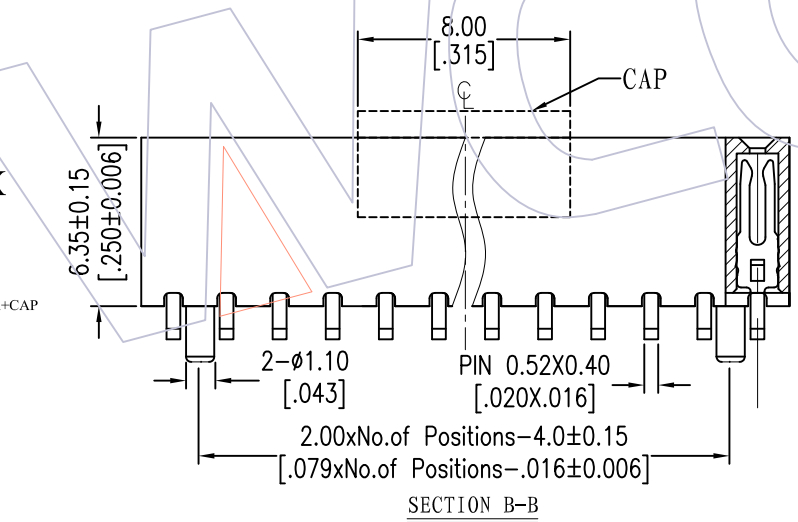
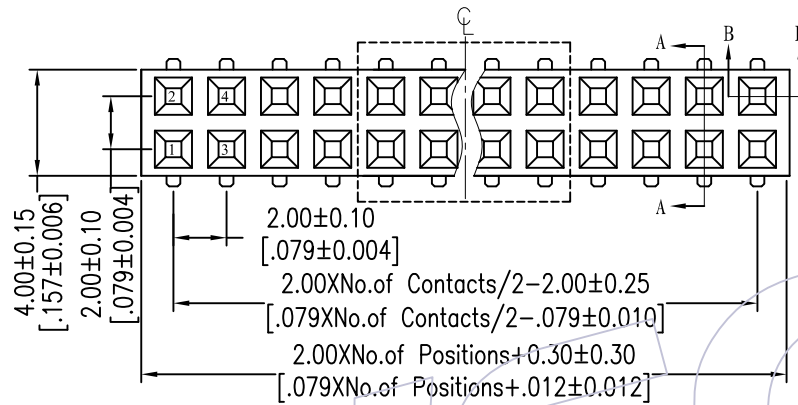
Contact Material: Phosphor Bronze  
 Contact plating: Au Or Sn over Ni  
 Insulator Material: LCP+30%G.F UL94V-0



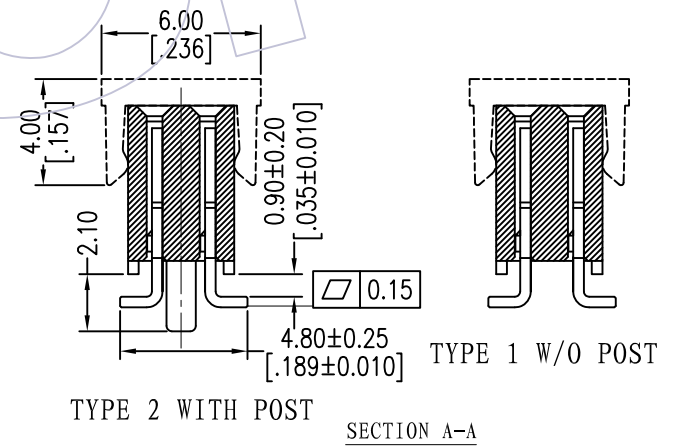
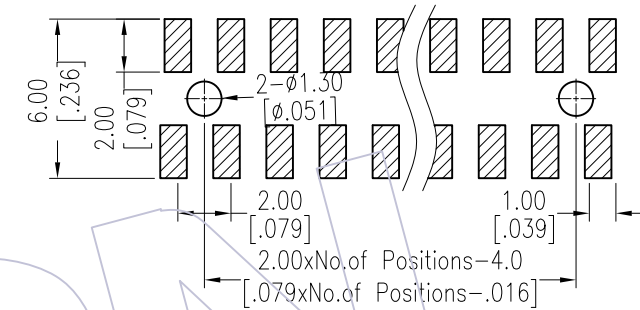
## Ordering Information

2263 - 2 XX M XX D Y N T X

No. of Pins per ROW: 02-40PIN  
 Contact Plating:  
 G0=Gold Flash  
 G3=10μ"Gold  
 G4=15μ"Gold  
 G5=30μ"Gold  
 S0=Gold Flash/Tin  
 S3=10μ"Gold/Tin  
 S4=15μ"Gold/Tin  
 S5=30μ"Gold/Tin  
 SN=Tin  
 SM=Matte Tin  
 Insulator:  
 D=LCP  
 Packing:  
 T=Tube  
 P=Tube+CAP  
 R=Tape&Reel+CAP



### Recommended P.C.B Layout (Top Side) (PCB BOARD TOLERANCE $\pm 0.05$ )



Item	Pitch	Mating
Standard	2.00	1215/1220
Alternate		

TITLE	PART NO.
TYPE 1	2263-2XXMXXDYNT1
TYPE 2	2263-2XXMXXDYNT2

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION		DRAW Wang	DATE	SCALE	FIT	PART NO.
				X.X	$\pm 0.40$					
A1	2013/03/15	Modify drawing	-----	X.XX	$\pm 0.25$	CHECK	2013/03/15	UNIT	mm	SEE TABLE
A0	2012/07/23	NEW	-----	X.XXX	$\pm 0.15$	APPROVE	DATE	SIZE	A4	TITLE: FH2.00mm DUAL ROW 180° SMT H=6.35
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	$\pm 3'$	APPROVE	DATE	SHEET	1/1	Customer NO.
				DIM	TOL			PROJ.		